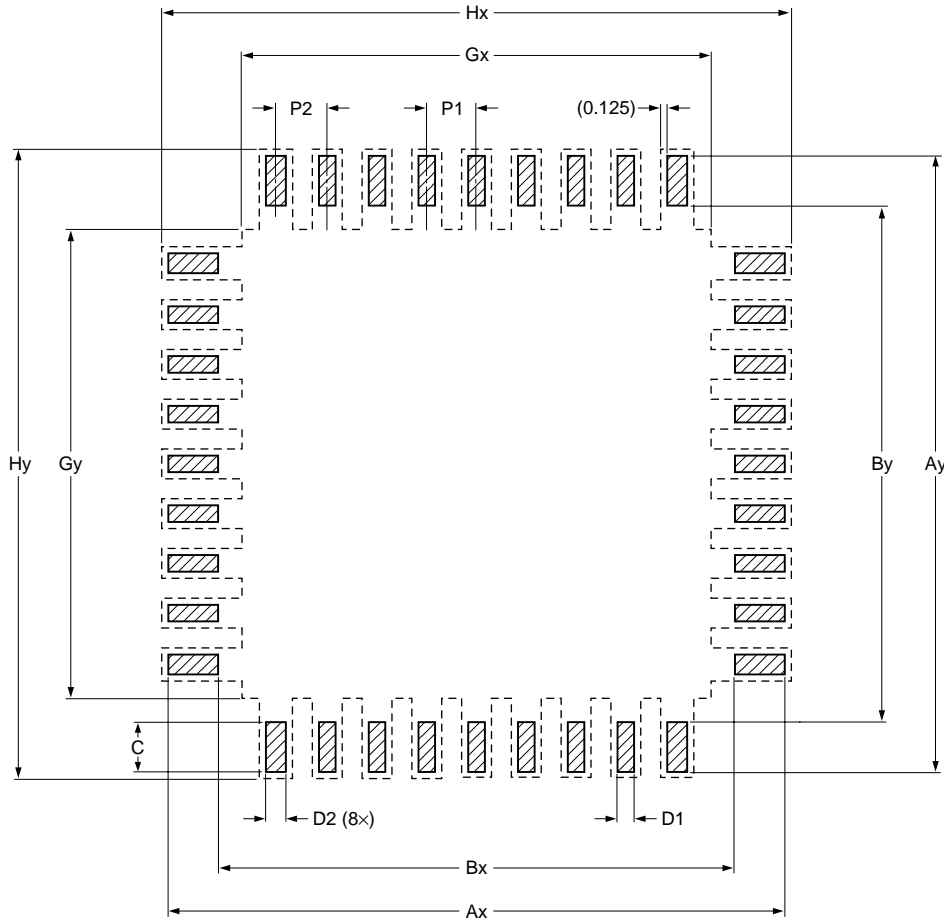




Footprint information for reflow soldering of LQFP128 package

SOT425-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	23.900	17.900	20.900	14.900	1.500	0.280	0.400	20.500	14.500	24.150	18.150